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	SEMI CONDUCTOR

#### **60V N-Channel Enhancement Mode MOSFET** SOP-8

Voltage

Current 8.3 A

### Features

• R<sub>DS(ON)</sub> , V<sub>GS</sub>@10V, I<sub>D</sub>@8.3A<17mΩ

60 V

- $R_{DS(ON)}$ ,  $V_{GS}$ @4.5V,  $I_D$ @4.0A<20m $\Omega$
- Advanced Trench Process Technology
- High density cell design for ultra low on-resistance
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

### **Mechanical Data**

- Case: SOP-8 package
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.0029 ounces, 0.083 grams

### **Maximum Ratings and Thermal Characteristics** (T<sub>A</sub>=25<sup>°</sup>C unless otherwise noted)

PARAMETER Drain-Source Voltage		SYMBOL	LIMIT	UNITS
		V <sub>DS</sub>	60	
Gate-Source Voltage		V <sub>GS</sub>	<u>+</u> 20	V
Continuous Drain Current	T <sub>A</sub> =25°C		8.3	
	T <sub>A</sub> =70°C	I <sub>D</sub>	6.6	А
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	33.2	
Power Dissipation	T <sub>A</sub> =25°C	_	2.5	
	T <sub>A</sub> =70°C	P <sub>D</sub>	1.6	W
Single Pulse Avalanche Energy (Note 5)		E <sub>AS</sub>	45	mJ
Operating Junction and Storage Temperature Range		T <sub>J</sub> ,T <sub>STG</sub>	-55~150	°C
Typical Thermal Resistance				
- Junction to Ambient <sup>(Note 6)</sup>		$R_{\theta JA}$	50	°C/W

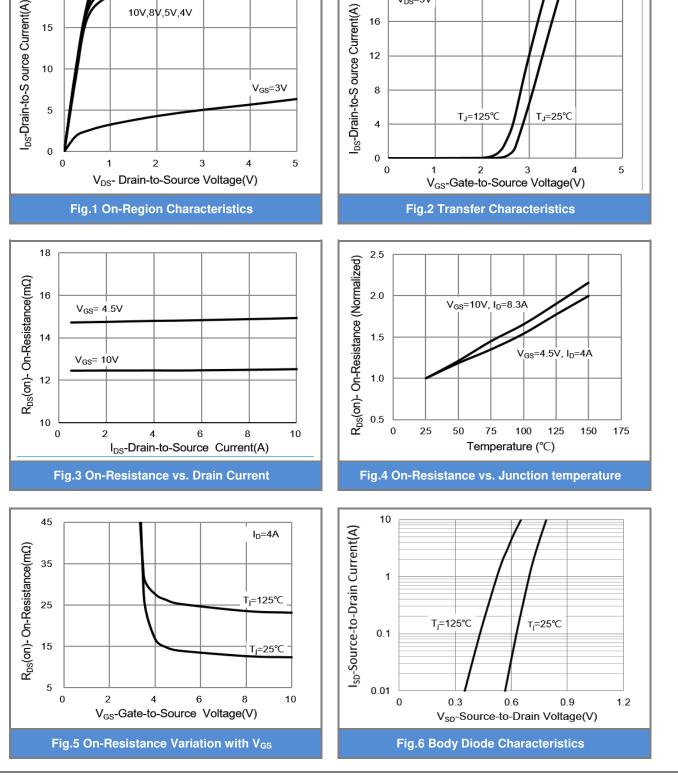


### **Electrical Characteristics** ( $T_A=25^{\circ}C$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}$ =0V, I <sub>D</sub> =250uA	60	-	-	V	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_{D}=250uA$	1.0	1.7	2.5	- V	
Drain-Source On-State Resistance	$R_{\text{DS(on)}}$	$V_{GS}$ =10V, I <sub>D</sub> =8.3A	-	14	17		
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}$ =4.5V, $I_{D}$ =4A	-	16	20	mΩ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ =60V, $V_{GS}$ =0V	-	-	1.0	uA	
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	<u>+</u> 100	nA	
Dynamic (Note 7)							
Total Gate Charge	$Q_{g}$	$V_{DS}$ =30V, I <sub>D</sub> =8.3A, $V_{GS}$ =4.5V <sup>(Note 1,2)</sup>	-	13.5	-		
Gate-Source Charge	$Q_{gs}$		-	4.8	-	nC	
Gate-Drain Charge	$Q_gd$		-	4.9	-		
Input Capacitance	Ciss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHZ	-	1574	-		
Output Capacitance	Coss		-	118	-	pF	
Reverse Transfer Capacitance	Crss		-	77	-		
Turn-On Delay Time	td <sub>(on)</sub>		-	11	-		
Turn-On Rise Time	tr	$V_{DD}$ =15V, $I_D$ =1A, $V_{GS}$ =10V, $R_G$ =6 $\Omega$ (Note 1,2)	-	11	-		
Turn-Off Delay Time	$td_{(off)}$		-	35	-	ns	
Turn-Off Fall Time	tf		-	8.1	-		
Drain-Source Diode			•	•	-		
Maximum Continuous Drain-Source	I <sub>s</sub>		-	-	8.3	A	
Diode Forward Current	-5						
Diode Forward Voltage	$V_{\text{SD}}$	I <sub>S</sub> =1A, V <sub>GS</sub> =0V	-	0.68	1	V	

NOTES :

- 1. Pulse width</br>
- 2. Essentially independent of operating temperature typical characteristics.
- 3. The maximum current rating is package limited.
- 4. Repetitive rating, pulse width limited by junction temperature TJ(MAX)=150°C. Ratings are based on low frequency and duty cycles to keep initial TJ =25°C.
- 5. The test condition is L=0.1mH,  $I_{AS}{=}30A,\,V_{DD}{=}25V,\,V_{GS}{=}10V$
- 6. R<sub>®JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper.
- 7. Guaranteed by design, not subject to production testing.



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V<sub>DS</sub>=5V

# PJL9436A1

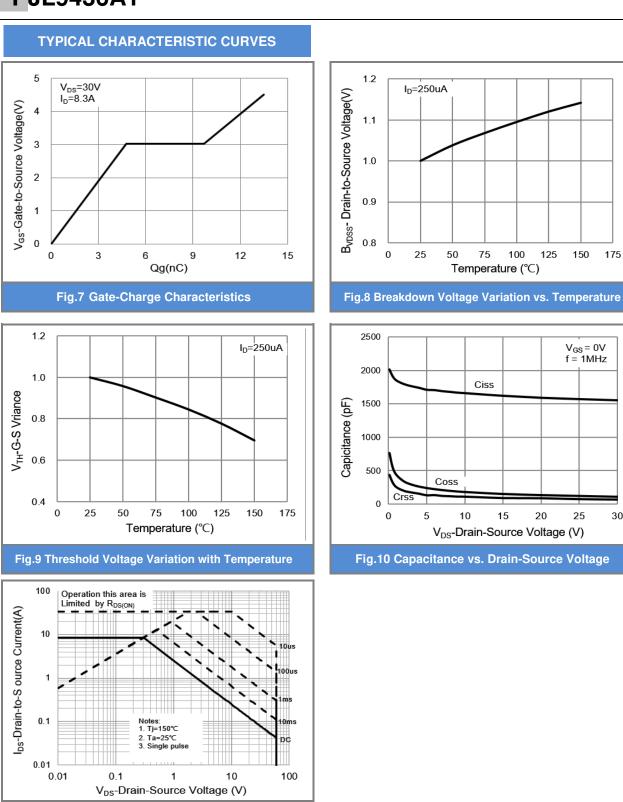
**TYPICAL CHARACTERISTIC CURVES** 

10V,8V,5V,4V

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Fig.11 Maximum Safe Operating Area



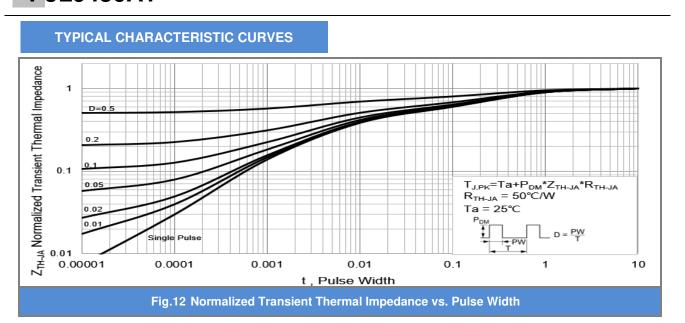






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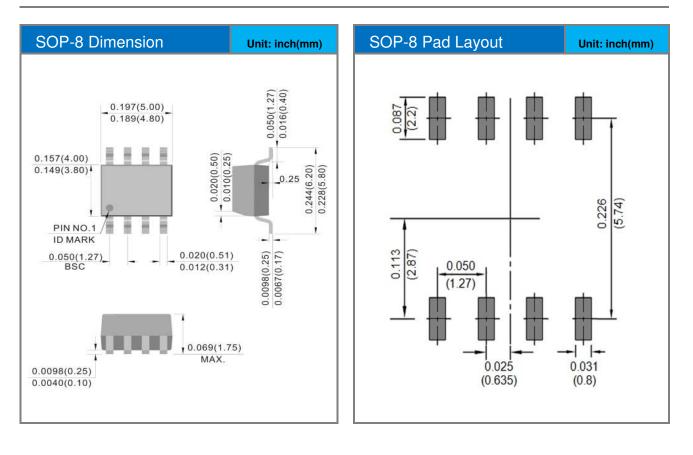
# 4



#### Part No Packing Code Version

Part No Packing Code	Package Type	Packing Type	Marking	Version
PJL9436A1_R2_00001	SOP-8	2.5K pcs / 13" reel	L9436A1	Halogen free

### Packaging Information & Mounting Pad Layout





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